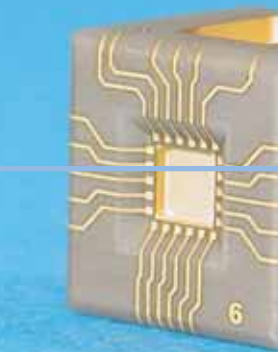


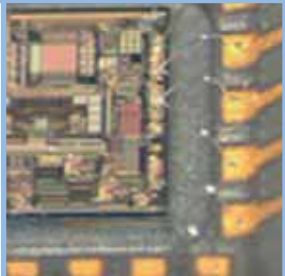


Alumina 3D interconnection device

CERAMIC COMPONENTS FOR THE MICROELECTRONICS



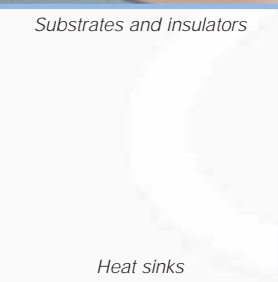
Aluminium nitride 3D interconnection device



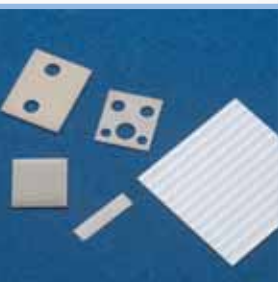
Example of a chip mounted onto a ceramic 3D interconnection device



Substrates and insulators



Heat sinks



Applications

- Electronics interconnection devices : 3D Packaging - Mechatronics - 3D MID
- Microwave components
- Microwave modules for antennas
- Sensors
- Ceramic packages

Products

- Insulators
- Heat sinks
- 3D interconnection devices
- Substrates
- Loads, absorbers, resonators...
- Grinding of ceramic packages

Materials

- Alumina (94 to 99,9 %)
- Aluminium nitride
- Quartz, glass
- Macor®
- Ferrites
- Dielectrics

Thin-film metallising

- Titanium, chromium
- Platinum, nickel
- Gold
- Silver
- Aluminium

